



- NOTES.
- 1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  - 2. SEAL AREA TO BE METALLIZED.
  - 3. DIE ATTACH AREA TO BE METALLIZED.
  - 4. SEAL RING TO BE FLOATING FROM ANY PINS.
  - 5. METALLIZED PADS TO BE ELECTRICALLY CONNECTED TO THEIR CORRESPONDING PINS.

MODIFICATION								FW006AC034-1 S=0			
								DRAWN	CHECKED	APPROVED	DATE
								Y.M	T.C/S.F	T.A	JAN.13.'94
								TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005		THIRD ANGLE PROJECTION	
CHANGED						DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN	
NAME 6 LEAD FLAT PACKAGE							MATERIAL AS INDICATED		DRAWING NO. KD-F94034		
SCALE 10/1							MATERIAL AS INDICATED		DRAWING NO. KD-F94034		SHEET 1/1

